



Material Content Data Sheet



Sales Product Name		BSS223PW H6327		Issued		31. July 2018		
MA#		MA001231712						
Package		PG-SOT323-3-2		Weight*		6.16 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.02		202	
	noble metal	gold	7440-57-5	0.005	0.08		781	
	inorganic material	silicon	7440-21-3	0.055	0.89	0.99	8856	9839
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		86	
	non noble metal	titanium	7440-32-6	0.003	0.04		432	
	non noble metal	chromium	7440-47-3	0.008	0.13		1295	
	non noble metal	copper	7440-50-8	2.647	42.99	43.17	429969	431782
wire	non noble metal	copper	7440-50-8	0.005	0.08	0.08	803	803
encapsulation	organic material	carbon black	1333-86-4	0.031	0.50		5008	
	plastics	epoxy resin	-	0.663	10.77		107666	
	inorganic material	silicondioxide	60676-86-0	2.389	38.81	50.08	388100	500774
leadfinish	non noble metal	tin	7440-31-5	0.133	2.16	2.16	21554	21554
plating	noble metal	silver	7440-22-4	0.217	3.52	3.52	35248	35248
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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